### **INTEGRATED CIRCUITS**

# DATA SHEET



# 74F299

8-bit universal shift/storage register (3-State)

**Product specification** 

1990 Mar 01

IC15 Data Handbook





### 8-bit universal shift/storage register (3-State)

74F299

#### **FEATURES**

- Common parallel I/O for reduced pin count
- Additional serial inputs and outputs for expansion
- Four operating modes: Shift left, shift right, load and store
- 3-State outputs for bus-oriented applications

#### **DESCRIPTION**

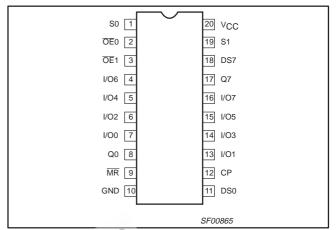
The 74F299 is an 8-bit universal shift/storage register with 3-State outputs. Four modes of operation are possible: Hold (store), shift left, shift right and parallel load. The parallel load inputs and flip-flop outputs are multiplexed to reduce the total number of package pins. Additional outputs are provided for flip-flops Q0 and Q7 to allow easy serial cascading. A separate active-Low Master Reset is used to reset the register.

The 74F299 contains eight edge-triggered D-type flip-flops and the interstage logic necessary to perform synchronous shift left, shift right, parallel load and hold operations. The type of operation is determined by S0 and S1, as shown in the Function Table. All flip-flop outputs are brought out through 3-State buffers to separate I/O pins that also serve as data inputs in the parallel load mode. Q0 and Q7 are also brought out on other pins for expansion in serial shifting of longer words.

A Low signal on  $\overline{\text{MR}}$  overrides the Select and CP inputs and resets the flip-flops. All other state changes are initiated by the rising edge of the clock. Inputs can change when the clock is in either state provided only that the recommended setup and hold times, relative to the rising edge of clock are observed.

A High signal on either  $\overline{\text{OE0}}$  or  $\overline{\text{OE1}}$  disables the 3-State buffers and puts the I/O pins in the high impedance state. In this condition the shift, hold, load and reset operations can still occur. The 3-State buffers are also disabled by High signals on both S0 and S1 in preparation for a parallel load operation.

#### PIN CONFIGURATION



TYPE	TYPICAL f <sub>MAX</sub>	TYPICAL SUPPLY CURRENT (TOTAL)
74F299	115MHz	58mA

#### **ORDERING INFORMATION**

	ORDER CODE	
DESCRIPTION	$ \begin{array}{c} \text{COMMERCIAL} \\ \text{RANGE} \\ \text{V}_{\text{CC}} = 5\text{V} \pm \! 10\%, \\ \text{T}_{\text{amb}} = 0^{\circ}\text{C to +} 70^{\circ}\text{C} \end{array} $	PKG DWG #
20-pin plastic DIP	N74F299N	SOT146-1
20-pin plastic SOL	N74F299D	SOT163-1
20-pin plastic SSOP II	N74F299DB	SOT339-1

#### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

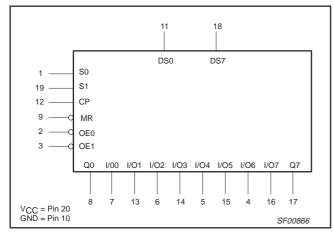
PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
DS0	Serial data input for right shift	1.0/1.0	20μA/0.6mA
DS7	Serial data input for left shift	1.0/1.0	20μA/0.6mA
S0, S1	Mode select inputs	1.0/2.0	20μA/1.2mA
СР	Clock pulse input (Active rising edge)	1.0/1.0	20μA/0.6mA
MR	Asynchronous Master Reset input (Active Low)	1.0/1.0	20μA/0.6mA
OE0, OE1	Output Enable input (Active Low)	1.0/1.0	20μA/0.6mA
Q0, Q7	Serial outputs	50/33	1.0mA/20mA
1/00	Multiplexed parallel data inputs or	3.5/1.0	70μA/0.6mA
I/On	3-State parallel outputs	150/40	3.0mA/24mA

NOTE: One (1.0) FAST Unit Load (U.L.) is defined as: 20μA in the High State and 0.6mA in the Low state.

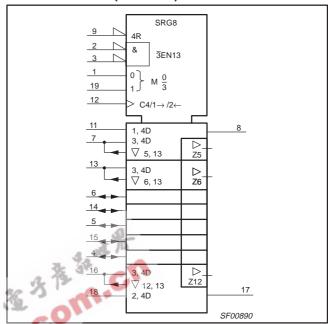
# 8-bit universal shift/storage register (3-State)

74F299

#### **LOGIC SYMBOL**



#### LOGIC SYMBOL (IEEE/IEC)



#### **FUNCTION TABLE**

INPUTS		INP	UTS		OPERATING MODE
<b>O</b> En	MR	S1	S0	СР	OPERATING MODE
L	L	X	X	Х	Asynchronous Reset; Q0 - Q7 = Low
L	Н	Н	Н	1	Parallel load; I/On $\rightarrow$ Qn (I/On outputs disabled)
L	Н	L	Н	1	Shift right; DS0 $\rightarrow$ Q0, Q0 $\rightarrow$ Q1, etc.
L	Н	Н	L	1	Shift left; DS7 $\rightarrow$ Q7, Q7 $\rightarrow$ Q6, etc.
L	Н	L	L	Х	Hold
Н	X	Х	Х	Х	Outputs in High Z

H = High voltage level

L = Low voltage level

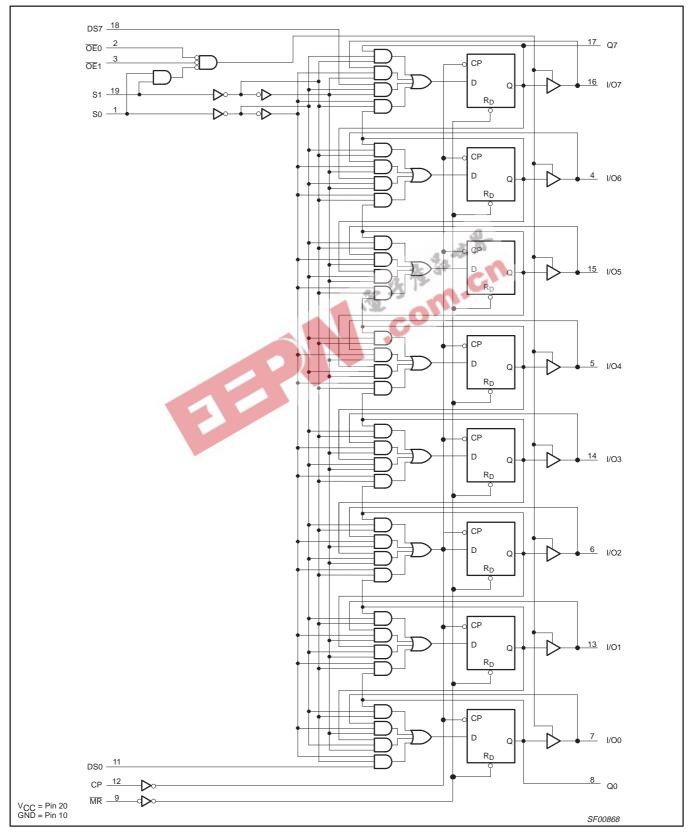
X = Don't care

↑ = Low-to-High clock transition

# 8-bit universal shift/storage register (3-State)

74F299

### **LOGIC DIAGRAM**



# 8-bit universal shift/storage register (3-State)

74F299

#### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V <sub>CC</sub>	Supply voltage		−0.5 to +7.0	V
V <sub>IN</sub>	Input voltage		-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA	
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to +V <sub>CC</sub>	V	
	Current applied to sustaint in Low sustaint state	Q0, Q7	40	mA
IOUT	Current applied to output in Low output state	48	mA	
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C	
T <sub>sta</sub>	Storage temperature		-65 to +150	°C

#### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER		. 47	5	LIMITS		UNIT
		-25-	44	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	· 41	- C	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage		Mr.	2.0			V
V <sub>IL</sub>	Low-level input voltage					0.8	V
I <sub>IK</sub>	Input clamp current					-18	mA
	High level output ourrent		Q0, Q7			-1	mA
ЮН	High-level output current		I/On			-3	mA
	Low level output a week		Q0, Q7			20	mA
I <sub>OL</sub>	Low-level output current		I/On			24	mA
T <sub>amb</sub>	Operating free-air temperature range			0		70	°C

### 8-bit universal shift/storage register (3-State)

74F299

#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

							LIMITS		
SYMBOL	PARAMETER		TEST C	CONDITIONS	O TAG	MIN	TYP NO TAG	MAX	UNIT
		Q0, Q7		1mΛ	±10%V <sub>CC</sub>	2.5			V
V	High-level output voltage	Q0, Q7	$V_{CC} = MIN,$	$I_{OH} = -1 \text{mA}$	±5%V <sub>CC</sub>	2.7	3.4		V
$V_{OH}$	Tilgii-level output voltage	I/On	$V_{IL} = MAX,$ $V_{IH} = MIN$	I <sub>OH</sub> = -3mA	±10%V <sub>CC</sub>	2.4			V
		1/011		IOH = -SIIIA	±5%V <sub>CC</sub>	2.7	3.3		V
V	Low-level output voltage		$V_{CC} = MIN,$		±10%V <sub>CC</sub>		0.35	0.50	<b>V</b>
$V_{OL}$	Low-level output voltage		$V_{IL} = MAX,$ $V_{IH} = MIN$	$I_{OL} = MAX$	±5%V <sub>CC</sub>		0.35	0.50	V
V <sub>IK</sub>	Input clamp voltage		V <sub>C</sub>	$C = MIN, I_I = I_{II}$	<		-0.73	-1.2	V
II	Input current at	others	V <sub>CC</sub>	= MAX, V <sub>I</sub> = 7.	0V			100	μΑ
	maximum input voltage	I/On	V <sub>CC</sub>	= 5.5V, V <sub>I</sub> = 5.	5V	J.,		1	mA
I <sub>IH</sub>	High-level input current	except I/On	V <sub>CC</sub>	$=$ MAX, $V_1 = 2$ .	7V 4	700		20	μΑ
	Low lovel input current	S0, S1	V	$=$ MAX, $V_I = 0$ .	EV	0	ĺ	-1.2	mA
I <sub>IL</sub>	Low-level input current	others	VCC	$= \text{IVIAX}, V_1 = 0.$	9 V			-0.6	mA
I <sub>IH +</sub> I <sub>OZH</sub>	Off-state output current, High-level voltage applied	I/On	V <sub>CC</sub> =	= MAX, V <sub>○</sub> = 2	7V			70	μΑ
I <sub>IL +</sub> I <sub>OZL</sub>	Off-state output current Low-level voltage applied	only	V <sub>CC</sub> :	$=$ MAX, $V_O = 0$	.5V			-0.6	mA
I <sub>OS</sub>	Short-circuit output current	NO TAG		$V_{CC} = MAX$		-60		-150	mA
		I <sub>CCH</sub>					55	60	mA
I <sub>CC</sub>	Supply current (total)	Iccl		$V_{CC} = MAX$			70	90	mA
		I <sub>CCZ</sub>					65	95	mA

#### NOTES:

<sup>1.</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.

Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

# 8-bit universal shift/storage register (3-State)

74F299

#### **AC ELECTRICAL CHARACTERISTICS**

						LIMIT	S		
SYMBOL	PARAMETER		TEST CONDITIONS	v	<sub>amb</sub> = +25° <sub>CC</sub> = +5.0° 50pF, R <sub>L</sub> =	V	V <sub>CC</sub> = +5	C to +70°C .0V ± 10% R <sub>L</sub> = 500Ω	UNIT
				MIN	TYP	MAX	MIN	MAX	
	Maximum alask fraguanay	I/O	Waveform 1	70	100		70		MHz
f <sub>MAX</sub>	Maximum clock frequency	Qn	vvavelorii i	85	115		85		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to Q0 or Q7	Waveform 1	4.0 4.5	5.0 6.0	7.5 8.0	3.5 4.5	8.5 8.5	ns ns	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to I/On		Waveform 1	4.0 4.0	6.0 6.5	9.0 9.0	4.0 4.0	10.0 10.0	ns ns
t <sub>PHL</sub>	Propagation delay MR to Q0 or Q7		Waveform 2	5.5	7.5	9.5	5.5	10.5	ns
t <sub>PHL</sub>	Propagation delay MR to I/On		Waveform 2	5.5	7.5	10.0	5.5	10.5	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable time Sn, OE to I/On		Waveform 4 Waveform 5	3.5 4.0	6.0 7.5	8.0 10.0	3.5 4.0	9.0 11.0	ns ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Disable time Sn, OE to I/On	Waveform 4 Waveform 5	2.5 1.5	4.5 2.5	7.0 5.5	2.5 1.5	8.0 6.5	ns ns	
C SETUR	PREQUIREMENTS			C	0.				

#### **AC SETUP REQUIREMENTS**

					LIMIT	s		
SYMBOL	PARAMETER	TEST CONDITIONS	V	<sub>amb</sub> = +25° / <sub>CC</sub> = +5.0° 50pF, R <sub>L</sub> =	V	T <sub>amb</sub> = 0°0 V <sub>CC</sub> = +5. C <sub>L</sub> = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time, High or Low S0 or S1 to CP	Waveform 3	6.5 6.5			7.5 7.5		ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, High or Low S0 or S1 to CP	Waveform 3	0 0			0 0		ns ns
$t_s(H)$ $t_s(L)$	Set-up time, High or Low I/On, DS <sub>L</sub> or DS <sub>R</sub> to CP	Waveform 3	3.5 3.5			4.0 4.0		ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, High or Low I/On, DS <sub>L</sub> or DS <sub>R</sub> to CP	Waveform 3	0 0			0		ns ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	CP Pulse width, High or Low	Waveform 1	5.0 4.5			5.0 4.5		ns
t <sub>w</sub> (L)	MR Pulse width, Low	Waveform 2	4.5			4.5		ns
t <sub>rec</sub>	Recovery time, MR to CP	Waveform 2	4.0			4.0		ns

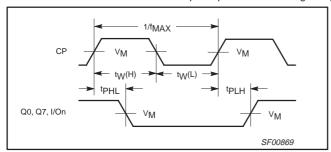
## 8-bit universal shift/storage register (3-State)

74F299

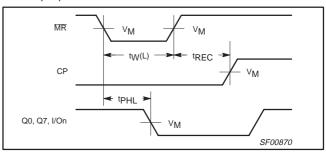
#### **AC WAVEFORMS**

For all waveforms,  $V_M = 1.5V$ 

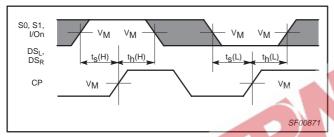
The shaded areas indicate when the input is permitted to change for predictable output performance.



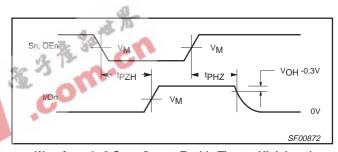
Waveform 1. Propagation Delay, Clock Input to Output, Clock Width, and Maximum Clock Frequency



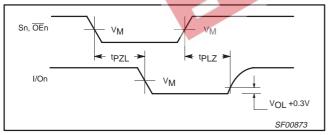
Waveform 2. Master Reset Pulse Width, Master Reset to Output Delay, and Master Reset to Clock Recovery Time



Waveform 3. Setup and Hold Times



Waveform 4. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 5. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

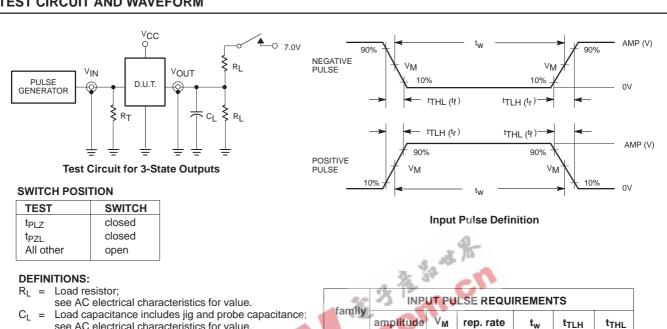
## 8-bit universal shift/storage register (3-State)

74F299

#### **TEST CIRCUIT AND WAVEFORM**

see AC electrical characteristics for value. Termination resistance should be equal to  $Z_{\rm OUT}$  of

pulse generators.



74F

3.0V

1.5V

1MHz

500ns

2.5ns

SF00777

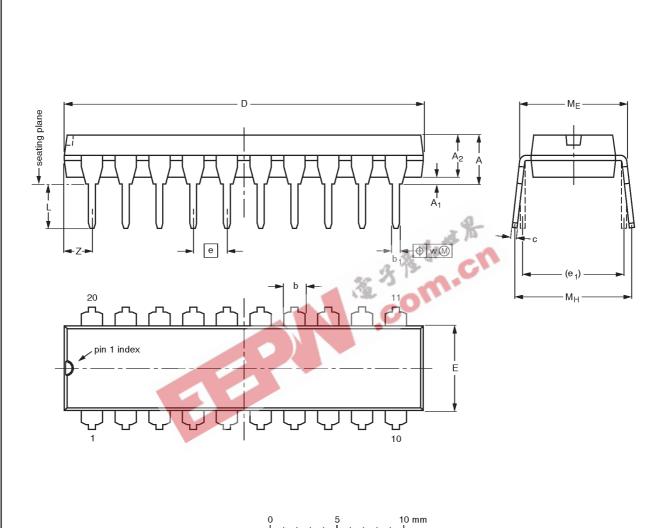
2.5ns

## 8-bit universal shift/storage register (3-State)

74F299

### DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



#### 0 5 10 mm scale

#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

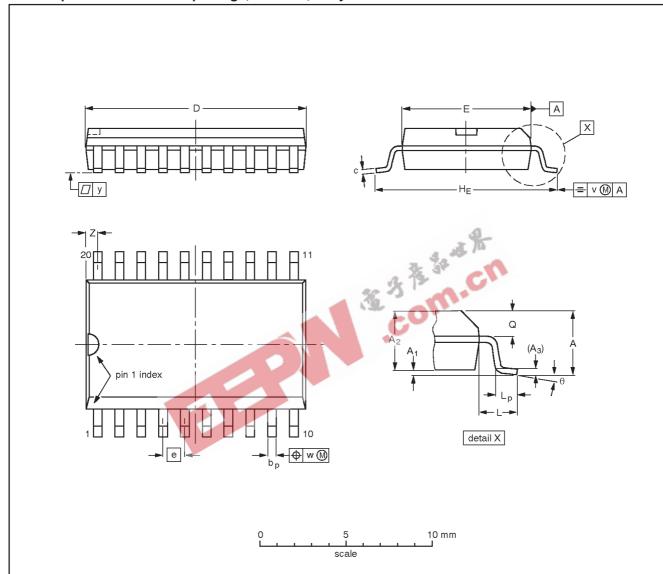
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT146-1			SC603		<del>92-11-17</del> 95-05-24

## 8-bit universal shift/storage register (3-State)

74F299

#### SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bр	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

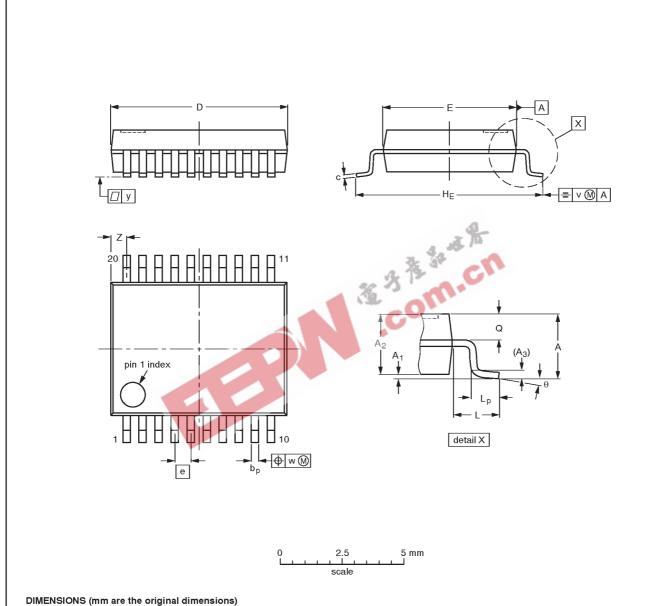
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT163-1	075E04	MS-013AC				<del>-95-01-24</del> 97-05-22

## 8-bit universal shift/storage register (3-State)

74F299

#### SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



UNIT	A max.	Α1	A <sub>2</sub>	А3	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

#### Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT339-1		MO-150AE				<del>-93-09-08</del> 95-02-04

## 8-bit universal shift/storage register (3-State)

74F299

#### **NOTES**



### 8-bit universal shift/storage register (3-State)

74F299

#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date.  Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

#### **Definitions**

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Application information** — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

#### **Disclaimers**

**Philips** 

Semiconductors

**Life support** — These products are not designed for use in life support appliances, devices or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Philips Semiconductors 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088–3409 Telephone 800-234-7381 © Copyright Philips Electronics North America Corporation 1998 All rights reserved. Printed in U.S.A.

print code Date of release: 10-98

Document order number: 9397-750-05117

Let's make things better.





